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**Inventor Information**

Inventor One Given Name:: Jun-ichiro  
Family Name:: FURIHATA  
Name Suffix::  
City of Residence:: Annaka-shi  
State or Prov. of Residence:: Gunma  
Country of Residence:: Japan  
Inventor Two Given Name:: Kiyoshi  
Family Name:: MITANI  
Name Suffix::  
City of Residence:: Annaka-shi  
State or Prov. of Residence:: Gunma  
Country of Residence:: Japan

**Correspondence Information**

Correspondence Customer Number:: 25944  
Name Line One:: Oliff & Berridge PLC  
Address Line One:: P.O. Box 19928  
City:: Alexandria  
State or Province:: VA  
Postal or Zip Code:: 22320  
Telephone:: (703) 836-6400  
Fax:: (703) 836-2787  
Electronic Mail:: commcenter@oliff.com

**Application Information**

Title Line One:: A METHOD OF PRODUCING A BONDED  
Title Line Two:: WAFER AND THE BONDED WAFER  
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**Continuity Information**

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**Prior Foreign Applications**

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